

SOT631-2

plastic low profile fine-pitch ball grid array package; 208 balls; body 15 x 15 x 1.05 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA208
Package type industry code	LFBGA208
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	14-8-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		14.9	-	15	15.1	mm
E	package width		14.9	-	15	15.1	mm
A	seated height		[tbd]	-	1.6	1.6	mm
A ₂	package height		0.95	-	1.05	1.2	mm
n ₂	actual quantity of termination		-	-	208	-	



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2. Package outline

LFBGA208: plastic low profile fine-pitch ball grid array package; 208 balls; body 15 x 15 x 1.05 mm SOT631-2

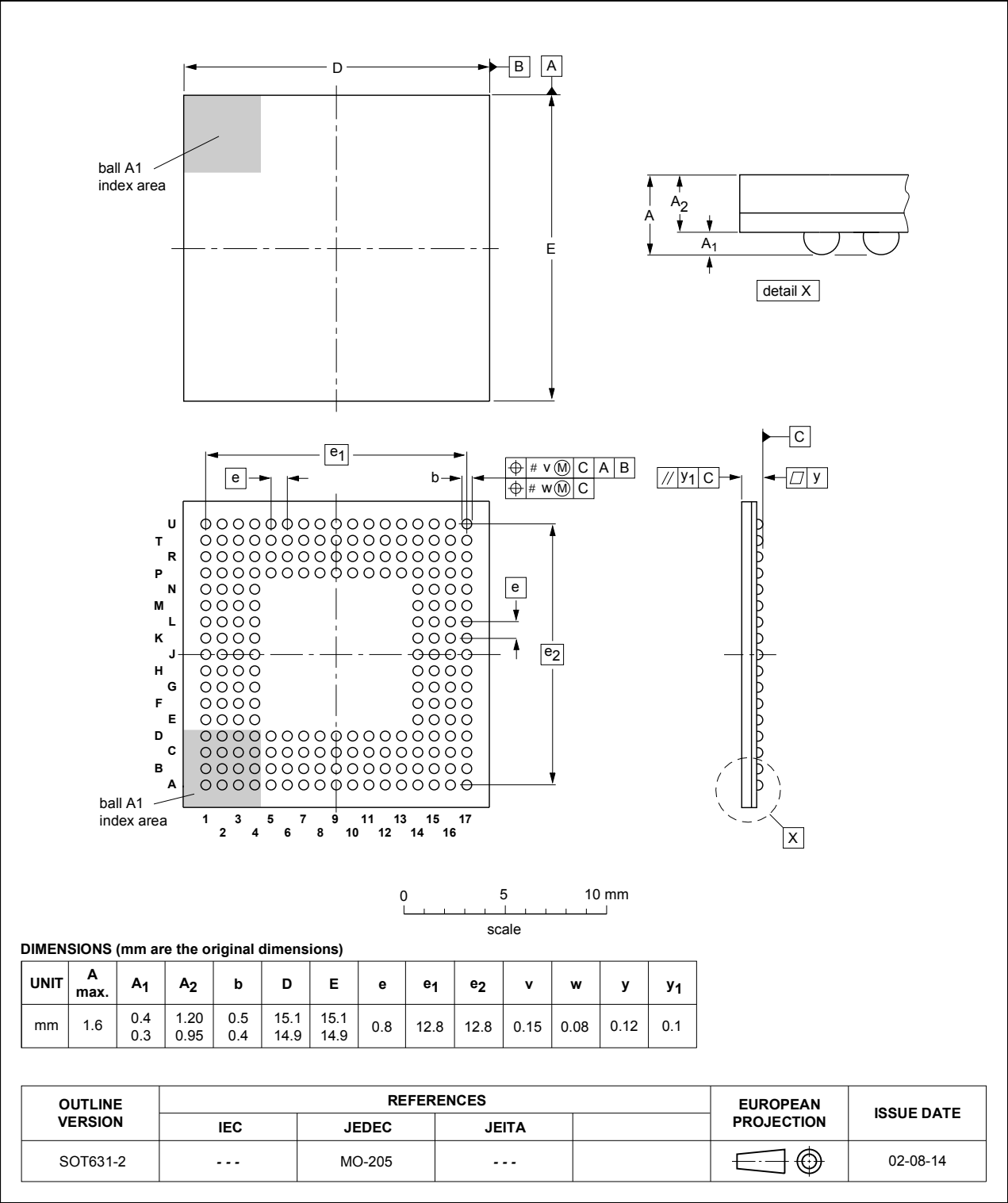


Fig. 1. Package outline LFBGA208 (SOT631-2)

3. Soldering

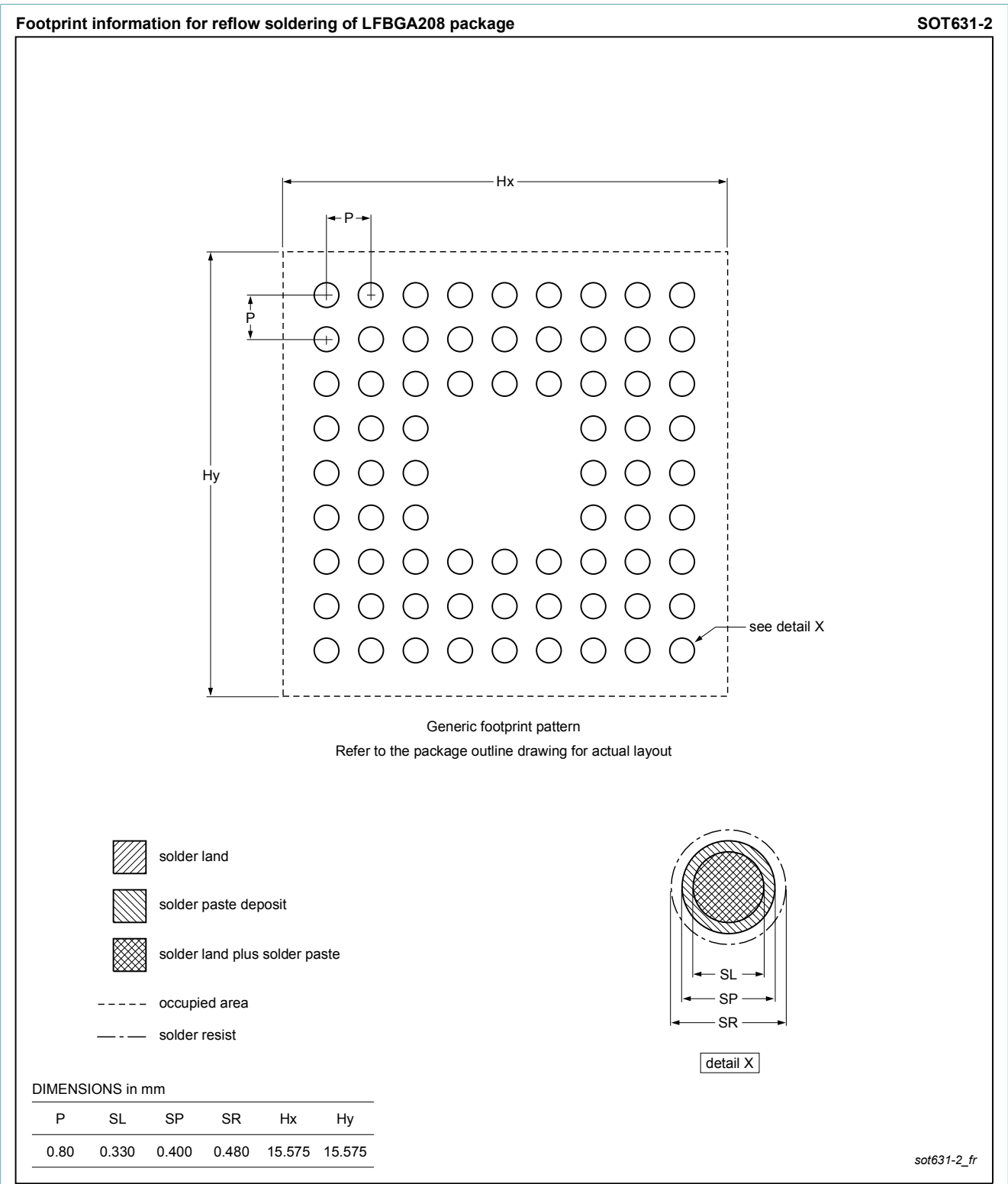


Fig. 2. Reflow soldering footprint for LFBGA208 (SOT631-2)

4. Legal information

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